

IN THE CLAIMS:

Please amend claims 1 and 2 as follows:

- Sub C1*
- 664207-EE-2100*
A2
1. (Amended) A multiple-die, low-profile semiconductor device comprising:
 - a. a lead-frame paddle supported by a lead frame;
 - b. a controlled, first, thin-adhesive layer of about 0.001 inches affixing a first die above the paddle;
 - c. a plurality of thin wires having a first low-loop wire bond to a plurality of first [diebonding] die-bonding pads, said first wire bond having a wire height above the [bonding pad] first die-bonding pads of about 0.006 inches, and a second wire bond to a plurality of adjacent lead-frame lead fingers;
 - d. a second thin-adhesive layer of about 0.008 inches affixing a second die above the first die;
 - e. a second plurality of thin wires having low-loop wire bonds to a plurality of - second die-bonding pads and second wire bonds to the plurality of lead fingers;
 - f. two additional dies affixed above the second die by additional subsequent layers of adhesive of about 0.008 inches and having additional thin wires bonded to additional bonding pads and lead fingers; and
 - g. an [encapsulated] encapsulation layer surrounding all dies, adhesive layers, and thin wires wherein a total encapsulated-package height is about 0.110 inches.
 2. (Amended) A multiple-die, low-profile semiconductor device comprising:
 - a. a lead-frame paddle supported by a lead frame;
 - b. a controlled, first, thin-adhesive layer of about 0.001 to 0.005 inches affixing a first die above the paddle;

- 42-1
C1 cont'd
- c. a plurality of thin wires having a first low-loop wire bond to a plurality of first die-bonding pads, said low-loop wire [ball] bond having a wire height above the first die-bonding pads of about 0.006 inches and a second wire bond to a plurality of adjacent lead-frame lead fingers;
 - d. a second thin-adhesive layer of about 0.008 to 0.010 inches affixing a second die above the first die;
 - e. a second plurality of thin wires having low-loop wire bonds to a plurality of second die-bonding pads and second wire bonds to the plurality of lead fingers;
 - f. an [encapsulated] encapsulation layer surrounding all die adhesive layers and thin wires wherein a total encapsulation-layer height is about 0.070 inches.
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REMARKS

No new matter has been added. The Applicant requests entry of the foregoing amendment prior to examination of the application on the merits.

Respectfully submitted,

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